

PATENT ASSIGNMENT COVER SHEET

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NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	DSM IP ASSETS B.V.	06/13/2014
RECEIVING PARTY DATA		
Name:	SEIKAGAKU CORPORATION	
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City:	TOKYO	
State/Country:	JAPAN	
Postal Code:	100-0005	
PROPERTY NUMBERS Total: 3		
Property Type	Number	
Application Number:	61309407	
Application Number:	14185639	
Patent Number:	8697398	
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SIGNATURE:	/Scott A. Schaller, #60,167/	
DATE SIGNED:	07/29/2014	
Total Attachments: 3		
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ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) or equivalent and other good and valuable consideration, receipt of which is hereby acknowledged, **DSM IP Assets B.V.**, a corporation formed under the laws of The Netherlands, having an office and place of business at Het Overloon 1, NL-6411 TE Heerlen, Netherlands (hereafter referred to as the "Assignor"), hereby sells and assigns to **SEIKAGAKU Corporation**, a corporation formed under the laws of Japan, having an office and place of business at 6-1, Marunouchi 1-chome, Chiyoda-ku, Tokyo, 100-0005 Japan (hereafter referred to as the "Assignee"), its entire right, title and interest for the United States of America (as defined in 35 U.S.C. § 100), Japan, Brazil, China, Europe, India, Korea, and throughout the world, including the right to sue for past infringement and to collect for all past, present and future damages,

(a) in each of the Patents and Patent Applications that are described in detail in Schedule A, annexed hereto and made a part hereof, and

(b) in any and all applications that claim the benefit of the Patents and Patent Applications described in detail in Schedule A, including non-provisional applications, continuing (continuation, divisional, or continuation-in-part) applications, reissues, extensions, renewals, and reexaminations of such Patents and Patent Applications, to the full extent of the term or terms for which Letters Patents issue, and

(c) in any and all inventions described in each of the Patents and Patent Applications that are described in detail on Schedule A, and in all forms of intellectual and industrial property protection derivable therefrom, and that are derivable from any and all continuing applications, reissues, extensions, renewals and reexaminations of such Patents and Patent Applications, including, without limitation, patents, applications, utility models, inventor's certificates, and designs together with the right to file applications therefor; and including the right to claim the same priority rights from any previously filed applications under the International Agreement for the Protection of Industrial Property, or any other international agreement, or the domestic laws of the country in which any such application is filed, as may be applicable;

all such rights, title and interest to be held and enjoyed by the above-named Assignee, its successors, legal representatives and assigns to the same extent as all such rights, title and interest would have been held and enjoyed by the Assignor had this assignment and sale not been made.

The Assignor agrees to execute all papers necessary in connection with the applications and Letters Patents as above, and any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue, reexamination or corresponding applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The Assignor agrees to execute all papers necessary in connection with any interference or patent enforcement action (judicial or otherwise) related to the applications or Letters Patents or

any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue or reexamination application thereof and to cooperate with the Assignee at Assignee's expense in every reasonable way possible in obtaining evidence and going forward with such interference or patent enforcement act.


The Assignor agrees to perform all affirmative acts at Assignee's request and expense that may be necessary to obtain or ensure a grant of a valid patent to the Assignee.

The Assignor hereby represents that Assignor has full right and authority to convey the entire interest herein assigned, and that Assignor has not executed, and will not execute, any agreement in conflict therewith.

The Assignor and Assignee hereby grant the patent practitioners associated with **CUSTOMER NUMBER 26111** the power to insert in this assignment, including the attached Schedule A, any further information regarding the patents and patent applications so identified in such Schedule A that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office or the patent offices of other jurisdictions for recordation of this document.

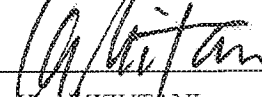
SIGNED on behalf of the said ASSIGNOR,

DSM IP ASSETS B.V.

By: 
Name: Birgit Rabanus
Title: Senior Director Patents
Date: 13 June 2014

SIGNED on behalf of the said ASSIGNEE,

SEIKAGAKU CORPORATION

By: 
Name: Ken MIZUTANI
Title: President
Date: 22 July 2014

SCHEDULE A

UNITED STATES PATENTS, UNITED STATES PATENT APPLICATIONS AND INTERNATIONAL APPLICATIONS THAT DESIGNATE THE UNITED STATES

	Application No.	Filing Date	Patent No.	Issue Date
1.	61/309,407	March 1, 2010		
2.	13/038,326	March 1, 2011	8,697,398	April 15, 2014
3.	14/185,639	February 20, 2014		
4.	PCT/US2011/026748	March 1, 2011		

OTHER INTERNATIONAL APPLICATIONS

	Country	Application No.	Filing Date
1.	Japan	2012-556184	March 1, 2011
2.	Brazil	1120120219952	March 1, 2011
3.	China	201180022154.5	March 1, 2011
4.	Europe	11751231.9	March 1, 2011
5.	India	8330/DELNP/2012	March 1, 2011
6.	Korea	10-2012-7025916	March 1, 2011